



Serial No. : 2016-0440

DATE : 2016/05/17

ITEM :

CRYSTAL OSCILLATOR

TYPE : DSO221SHF

NOMINAL FREQUENCY : 24.000MHz

SPEC No. : 1XSF024000EHC

Please acknowledge receipt of this specification by signing and returning a copy to us.

RECEIPT	
DATE	
RECEIVED	(signature) (name)

General Manufacturer of Quartz Devices

DAISHINKU CORP.

1389 Shinzaike, Hiraoka-cho, Kakogawa, Hyogo
675-0194 Japan
Phone (81)79-425-3141 Fax (81)79-425-1134
http://www.kds.info/index_en.htm

C.ENG. *S. Shigematsu*

ENG. *E. Kamada*

1. **Device Name** SPXO (Output Load Condition C-MOS)
2. **Type Name** DSO221SHF
3. **Nominal Frequency** 24.000MHz

4. Absolute Maximum Ratings

Item	Symbol	Value	Unit
Vcc terminal voltage	V_{CC}	-0.6~+6.0	V
Input terminal voltage	V_{IN}	-0.6~ V_{CC} +0.6	V
Output terminal voltage	V_{OUT}	-0.6~ V_{CC} +0.6	V
Output terminal current	I_{OUT}	10	mA
Storage temp. range	T_{stg}	-40~+85	°C

5. Electric Specifications

Item	Symbol	Value			Unit	Condition	
		min.	typ.	max.		V_{CC}	Temp.
Total Frequency tolerance	f_{tol}	-50	-	+50	ppm	+1.8±0.2V	-10~+70°C
Operating temp. range	T_{use}	-10	+25	+70	°C		-
Supply voltage	V_{CC}	+1.6	+1.8	+2.0	V	-	-10~+70°C
Current consumption(No Load) (#1 Pin:Open or "H")	I_{CC}	-	-	2.8	mA	+1.8V	+25±3°C
Standby Current (#1 Pin : "L")	I_{std}	-	-	0.01	mA		
Symmetry (Duty Cycle)	SYM	45	50	55	%		
Low level output voltage	V_{OL}	-	-	$V_{CC} \times 0.1$	V		
High level output voltage	V_{OH}	$V_{CC} \times 0.9$	-	-	V		
Rise & Fall time	t_r / t_f	-	-	6	ns		
Output Load	L_{CMOS}	-	-	15	pF		
Low level input current	I_{IL}	-	-	-0.01	mA		
High level input current	I_{IH}	-	-	0.01	mA		
Low level input voltage	V_{IL}	-	-	$V_{CC} \times 0.2$	V		
High level input voltage	V_{IH}	$V_{CC} \times 0.8$	-	-	V		
Output disable time	tPLZ	-	-	150	ns		
Output enable time	tPZL	-	-	1	ms		

Measurement circuit and output wave form is refer to Fig.1. and Fig.2.

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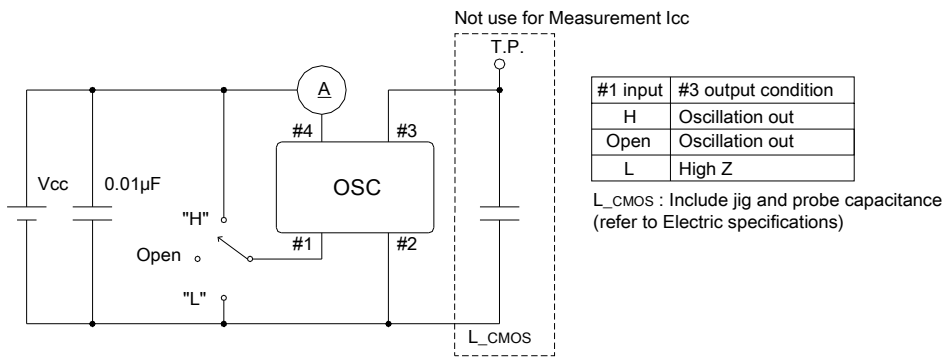


Fig.1. Measurement circuit

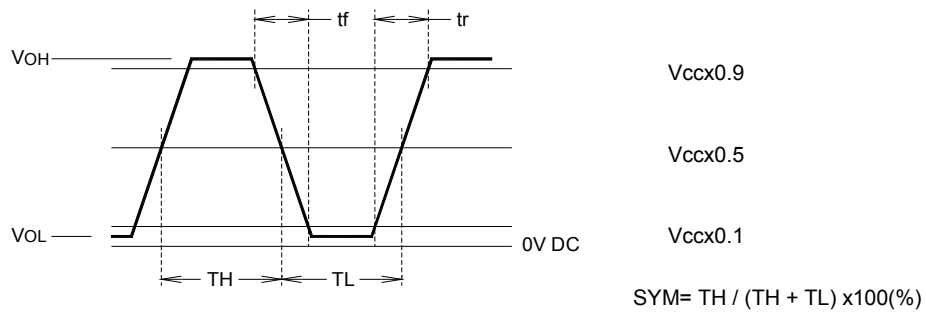


Fig.2. Output wave form

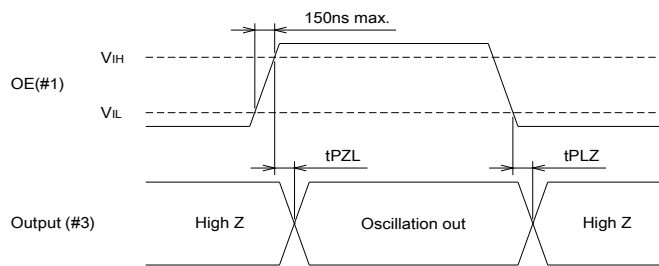
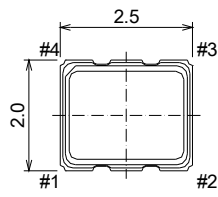


Fig.3. Input output condition

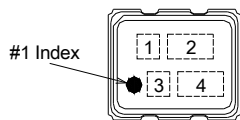
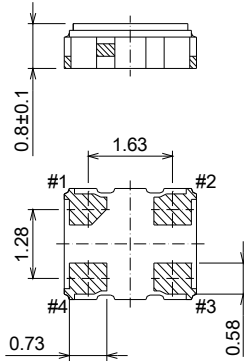
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6. Dimensions



Pin Connections	
Pin No.	Connection
#1	OE(Output Enable)
#2	GND
#3	Output
#4	Vcc

Tolerance: ± 0.15
unit: mm



Type code(1) should be printed as follows by producing district

Type	Marking
DSO221SHF	HF

Nominal Frequency (2) and Logo(3) should be printed as follows by producing district

Made in JAPAN → Spec.No. : 1XSF024000EHC Frequency : 24.0 Logo : D

Manufacturing lot No.(4)(Year and Week):3 numbers as follows

Year : The last digit of the year

Week : We gave the sequence of week numbers 01(first week) for production date.

There are starting from 1st of Jan. However, add '0' figure to the first week during the nine weeks.

The week means are from Sunday to Saturday.

Example 2016/5/19 : 6 21
 year week

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7. Mechanical Performance

- 7.1 Natural Drop
Drop 3 times from the height of 50cm onto min. 30mm thickness hard wooden board.
The component shall satisfy requirement of the electrical characteristics.
- 7.2 Resistance impact
6ms/1000m/s² to X,Y and Z axes (6 directions), 3cycles.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 7.3 Vibration
Frequency 10 ~ 55Hz, Sine Wave full amplitude of 1.5mm to X, Y and Z axis, Duration of 2h to each axis.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 7.4 Sealing Tightness
Leak Rate 1.0×10^{-9} Pa m³/s max. measured by Helium leak detector.
And no bubble continued (1 time max.) in Fluorinert at +125± 5°C.
- 7.5 Solderability
After applying ROSIN Flux, dipping in solder bath at +245± 5°C for 5s.
Over 90% of terminal shall be covered by solder.

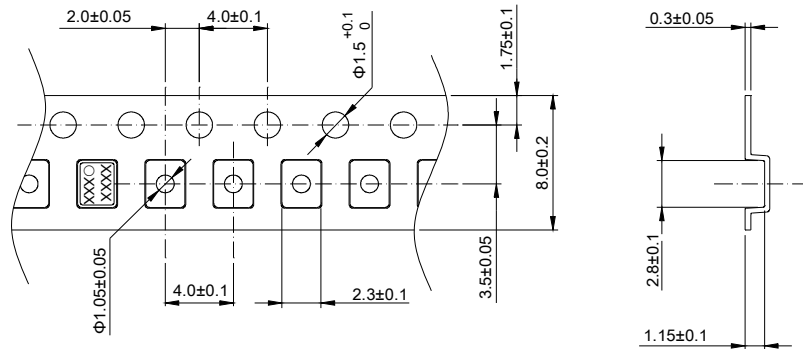
8. Environment Performance

- 8.1 Humidity
Temperature +60± 2°C RH 90 ~ 95 %, Duration of 240h.
Back to the room temperature first, then in 24h, the component shall be checked.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 8.2 Storage in Low Temperature
Lower Operating temperature ± 3°C Duration of 240h.
Back to the room temperature first, then in 24h, the component shall be checked.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 8.3 Storage in High Temperature
Upper Operating temperature ± 2°C Duration of 240h.
Back to the room temperature first, then in 24h, the component shall be checked.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 8.4 Temperature cycles
Lower Operating temperature ± 3°C (30 min) <-> Upper Operating temperature ± 2°C (30 min)
20 cycles. Back to the room temperature first, then in 24h, the component shall be checked.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- 8.5 High Temperature Operation
Upper Operating temperature ± 2°C maximum V_{CC} Duration of 240h.
Back to the room temperature first, then in 24h, the component shall be checked.
The component shall satisfy requirement of the electrical characteristics. No physical damage.
- (*) Upper Operating temperature: Case of +85°C max. -> +85°C
(*) Lower Operating temperature: Case of -30°C max. -> -30°C
- 8.6 Static Electricity
Antistatic electrical intensity level
- | | |
|-------------------------------|-------------------|
| Test Conditions | Breakdown Voltage |
| (MM) C=200pF, R=0Ω | ±200 V |
| (HBM) C=100pF, R=1.5kΩ | ±2000 V |
| Number of times : 3times max. | |
- The component shall satisfy requirement of the electrical characteristics. No physical damage.

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9. Taping and Packing

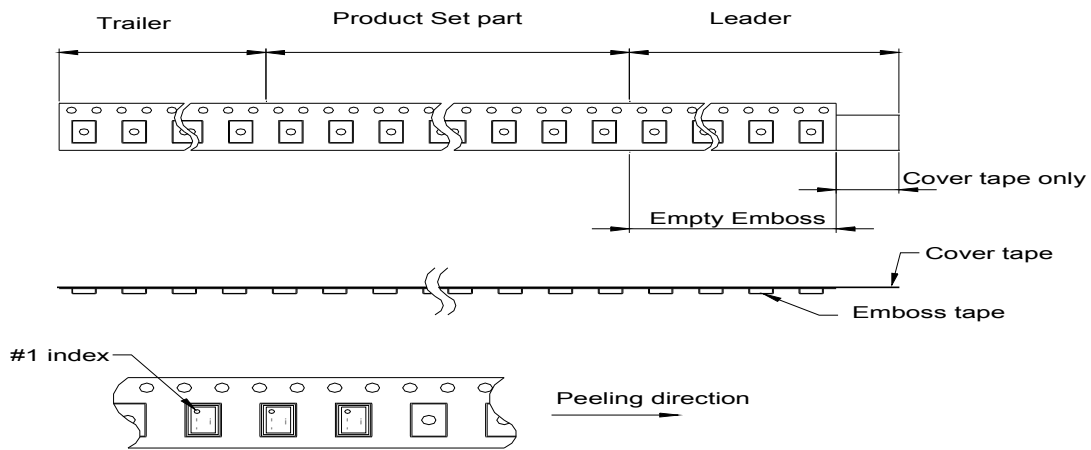
9.1 Emboss Tape specifications



Material:PS(Conductivity)
unit:mm

9.2 Joint of Tape

Emboss Tape and cover tape should not be jointed.



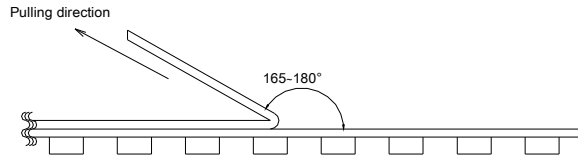
9.3 Taping Dimension

Leader	Cover tape	The length of cover tape in the leader is more than 400mm including empty emboss area.
	Emboss tape	After all products were packaged, must remain more than twenty pieces or 400mm empty area, which should be sealed by cover tape.
Trailer	Cover tape	The trailer area which are sealed by cover tape must remain more than 350mm.
	Emboss tape	

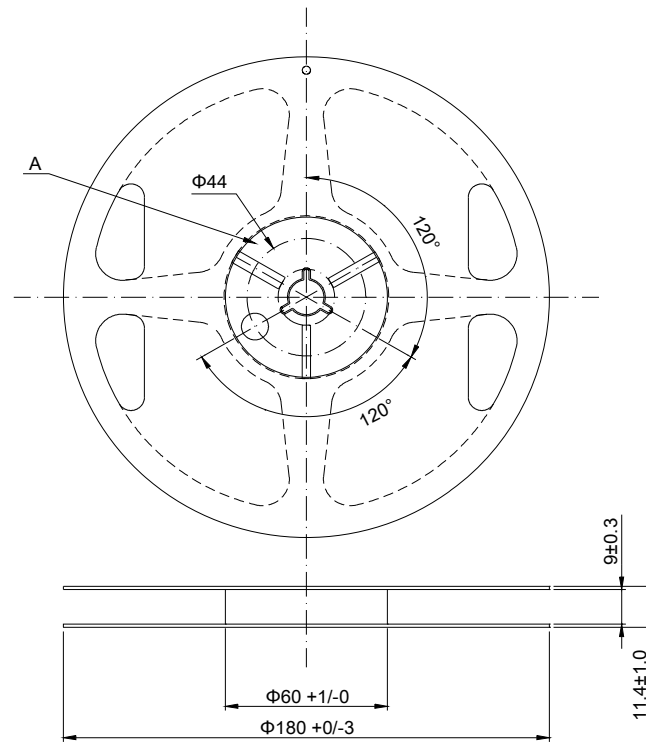
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9.4 Peeling Strength of Cover tape

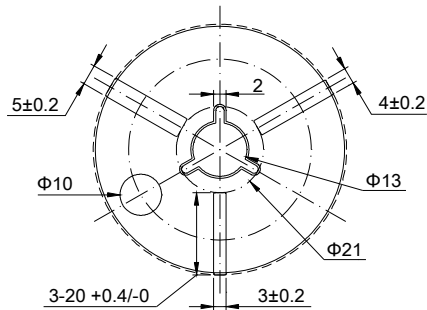
The peeling strength of cover tape pulls and keep to angle 165~180° and make limit 0.1~ 0.7N without prescription, when it pulled it with the speed of 300mm/min. (Others conform to JIS C 0806_1990)



9.5 Reel specifications



A Part




Material:PS(Conductivity)
unit: mm

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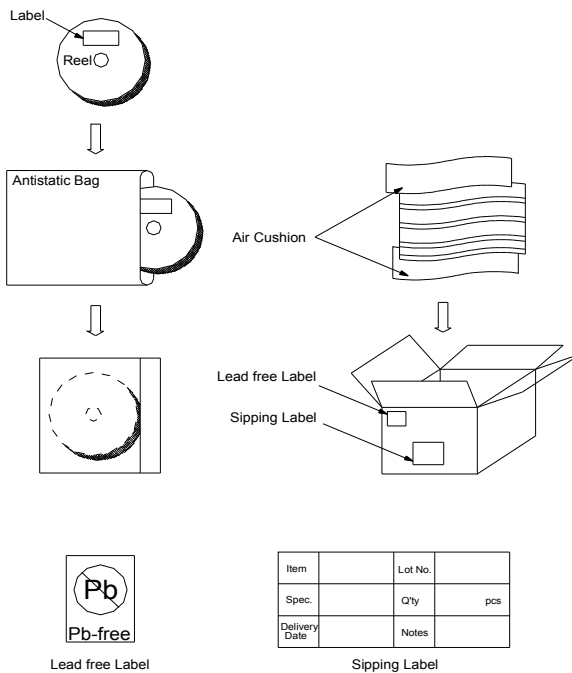
9.6 Storage
 Temperature+40°C max. Humidity80% max.

9.7 Quantity on reel
 2000pcs. / reel

9.8 Label
 Label is following information. Printing Label at each reel.

TYPE	*****	The type of product
SPEC	*****	Our specification No.
No.		
PARTS	*****	Your Part No.
No.		
LOT	***** **	Lot No.
No.		
FREQ.	***** **	Nominal Frequency
Q'TY	****	Quantity
KDS 		Producing country name
MADE IN JAPAN		

9.9 Shipping carton
 Packed in a carton box. The following label on the side of carton box.



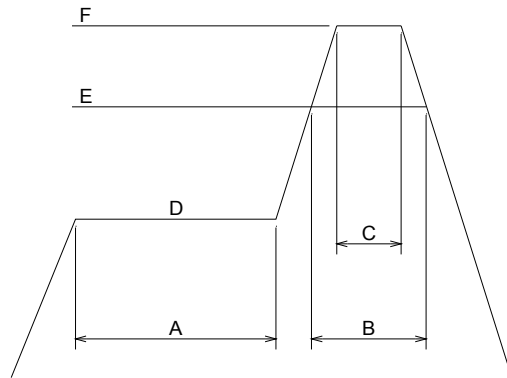
(*) The product is packed up with the method which does not break in the handling by a shipping agent.

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10. Supplement

10.1 Reflow Soldering (Example)

Please stay with our proposed reflow condition and do then soldering 2 times max.

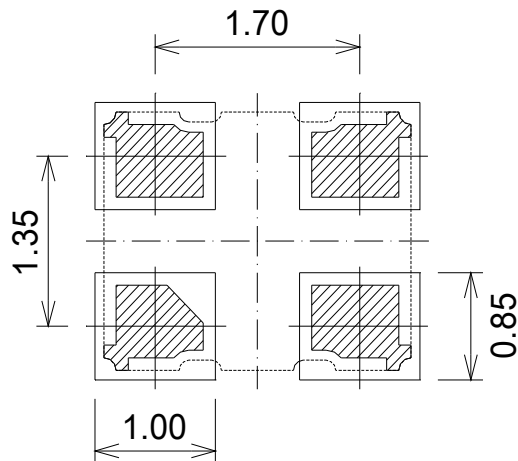


A:Pre Heat	120 s
B:Heat	60 s
C:Peak	10 s max.
D:Pre Heat temp.	+160 ~ +180 °C
E:Heat temp.	+220 °C
F:Peak temp.	+260 °C

10.2 Solder iron(Example)

Bit temp.: +350°C max., Time:5s max., Each terminal solder a 1 time max.

10.3 Land pattern layout (Example)



unit:mm

10.4 Mounting

This component is designed for automatic insertion.

However you are requested to do the trial with your insertion machine in order to be sure of proper operation and no damage of component.

Please pay attention to board warp which may damage the component and cause soldering process.

Please mount so that the metalize side and other electrical conductivity structures (a main part lid is included) of the base side do not contact electrically.

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- 10.5 Cleaning
 Cleaning liquid which corrodes Nickel shall not be used. It may cause the problem on the surface color marking etc. Ultrasonic cleaning is possible however you are requested to check on your board. Because we only checked as single unit.

- 10.6 Handling
 This product is designed to withstand Drop and Vibration, however, the crystal blank might be broken. So if excess force is given, please check the characteristics before use. This product has C-MOS circuit inside. Please pay attention to latch-up, static-electricity as same handling as other C-MOS devices.

- 10.7 By-pass Capacitor
 It has no by-pass capacitor integrated. we recommend you to use capacitor (like ceramic chip capacitor) 0.01μF in-between Vcc and GND.

- 10.8 Storage
 Please keep away from high temperature and high humidity, which may cause put solderbility. No direct Sunlight. No dew as well.

- 10.9 Thrust an ultrasonic cleaning
 Because It use a small, thin crystal piece depending on a condition, the inside does resonance, and there is fear to cause the non-oscillation. When it's the worst, it may be destroyed. About the ultrasonic cleaning, it is use in the implementation of your company is in a state and confirming a thing without the influence in the appearance and a characteristic beforehand.

- 10.10 Point out supersonic wave welding
 It can't recommend implementation by the supersonic wave welding and the processing so that the vibration excessive inside of the crystal oscillator propagates, and there is a threat that It cause characteristic deterioration and the non-oscillation.

- 10.11 RoHS Compliance
 These Products do not contain the six substances restricted and prohibited on the restriction of the use of certain hazardous substances in electrical and electronic equipment.(DIRECTIVE 2011/65/EU OF THE EUROPIAN PARLIAMENT AND OF THE COUNCIL)

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